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As the below-named inventor, I declare that:

My residence, post office address, and citizenship are as stated below under my name.

I believe I am the original, first, and sole inventor of the subject matter claimed and for which a patent is sought on the invention entitled "PLANARIZING MACHINES AND METHODS FOR DISPENSING PLANARIZING SOLUTIONS IN THE PROCESSING OF MICROELECTRONIC WORKPIECES" in the foregoing specification and claims.

I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment specifically referred to above.

I acknowledge my duty to disclose information which is material to the patentability of this application in accordance with 37 C.F.R. § 1.56(a).

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that the making of willfully false statements and the like is punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and may jeopardize the validity of any patent issuing from this patent application.

Residence City of Boise

State of Idaho

Citizenship United States of America

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